External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped Silicon	Silicon (Si)	7440-21-3	0.05193	100.0	1
			Subtotal	0.05193	100	1
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.01377	100.0	0.26507
	Pure metal	Aluminium (Al)	7429-90-5	0.16618	100.0	3.2
			Subtotal	0.17995	200	3.46507
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.0275	0.04	0.52948
	Copper alloy	Iron (Fe)	7439-89-6	0.06874	0.1	1.3237
	Copper alloy	Copper (Cu)	7440-50-8	68.64365	99.86	1,321.84682
			Subtotal	68.73989	100	NaN
Mould Compound		Bisphenol-A Bisphenol-A Diglycidyl Ether copolymer	25036-25-3	0.37974	1.3	7.3125
	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	2.04475	7.0	39.375
	Polymer	Epichlorohydrin/o-Cresol/Formaldehyde polymer (generic)	29690-82-2	4.0895	14.0	78.75
	Filler	Silica fused	60676-86-0	1.75264	6.0	33.75
	Carbon Black	Carbon black	1333-86-4	0.11684	0.4	2.25
	Filler	Misc. Silica compounds (generic)	14808-60-7	20.44748	70.0	393.75
		Antimony Trioxide (Sb2O3) - cas no. 1309-64-4	1309-64-4	0.37974	1.3	7.3125
			Subtotal	29.21069	100	562.5
Post-plating	Pure Metal	Tin (Sn)	7440-31-5	1.40211	100.0	27
			Subtotal	1.40211	100	27
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.02077	5.0	0.4
	Lead alloy	Silver (Ag)	7440-22-4	0.01039	2.5	0.2
	Lead alloy	Lead (Pb)	7439-92-1	0.38428	92.5	7.4
			Subtotal	0.41544	100	8
			Total	100.00001	100	NaN

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